

LEAD-FREE SOLDER AND SOLDERED ARTICLE

This is a divisional of U.S. Patent Application Serial Number  
09/632,819, filed August 7, 2000, <sup>now U.S. Patent No. 6,660,226,</sup> in the name of Hidekiyo TAKAOKA and  
Kiyotaka MAEGAWA and entitled LEAD FREE SOLDER AND  
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